



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-03-31
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	APMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
VIPERGAN100WBTR	NN0U*MY4EAA5	A	Z7GA	2025-03-31
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	70.80	mg	Each	ECOPACK® 3
Identity	Authority			
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
3	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0

Package designator	Package size	Number of instances	Shape
QFN	4.9x5.9	16	gull wing
Comment			
Comment	B0PH TFQFPN5X6 16L - PITCH 0.5		

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	Description

QueryList : California Prop65 list, dated 3rd January 2025	Response		
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen	false		
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen	true		
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.030	alloy	424

QueryList :Customer	Response
QUERY	Response

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014	Response			
QUERY	Response			
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products	false			
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products	false			
Hazardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
0	0	0	0	0

QueryList : REACH-21st January 2025	Response			
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	true			
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH	true			
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Tungsten,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	False

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration :						Mfr Item Name	NN0U*MY4EAA5	70.7991		5999962.0	999986.0	
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies or Wafer (choose)	M-011 Other inorganic materials	5.780	mg	supplier	die	Silicon(Si)	7440-21-3		5.169	mg	894291	73008
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.076	mg	13149	1073
				supplier	metallisation	Copper(Cu)	7440-50-8		0.143	mg	24740	2020
				supplier	metallisation	Gallium nitride	25617-97-4		0.087	mg	15052	1229
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.030	mg	5190	424
				supplier	metallisation	Silver(Ag)	7440-22-4		0.030	mg	5190	424
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.001	mg	173	14
				supplier	metallisation	Tungsten(W)	7440-33-7		0.026	mg	4498	367
				supplier	Passivation	Silicon nitride(S	12033-89-5		0.010	mg	1730	141
				supplier	passivation	Silicon oxide	7631-86-9		0.165	mg	28547	2331
				supplier	polymer coating	polyimide	proprietary		0.043	mg	7439	607
				Leadframe	M-004 Copper and its alloys	28.369	mg	supplier	alloy	Cu	7440-50-8	
supplier	alloy	Cr	7440-47-3						0.071	mg	2503	1003
supplier	alloy	Sn	7440-31-5						0.071	mg	2503	1003
supplier	alloy	Zn	7440-66-6						0.062	mg	2185	876
supplier	alloy	Ni	7440-02-0						0.359	mg	12655	5071
supplier	alloy	Pd	7440-05-3						0.028	mg	987	395
supplier	alloy	Au	7440-57-5						0.004	mg	141	56
Die attach	M-011 Other inorganic materials	5.678	mg	supplier	glue	Silver	7440-22-4		5.111	mg	900000	72183
				supplier	glue	Glycol Ether	Proprietary		0.284	mg	50000	4010
				supplier	glue	1,6-bis(2,3-epo	16096-31-4		0.284	mg	50000	4010
Bonding wires	M-004 Copper and its alloys	1.065	mg	supplier	wire	Cu	7440-50-8		1.040	mg	976450	14684
				supplier	wire	Pd	7440-05-3		0.022	mg	21000	316
	0	M-008 Precious metals			supplier	wire	Au	7440-57-5		0.003	mg	2550
Encapsulation	M-011 Other inorganic materials	23.890	mg	supplier	mold compound	Epoxy Resin	proprietary		1.242	mg	51995	17544
				supplier	mold compound	Phenol Resin	proprietary		0.248	mg	10399	3509
				supplier	mold compound	Silica (Amorphc	60676-86-0		21.083	mg	882492	297779
				supplier	mold compound	Silica (Amorphc	7631-86-9		1.242	mg	51995	17544
				supplier	mold compound	Carbon Black	1333-86-4		0.075	mg	3120	1053
Encapsulation 2		6.018	mg	supplier	mold compound	Fused Silica	60676-86-0		4.483	mg	745000	63325
				supplier	mold compound	Epoxy Resin	85954-11-6		0.903	mg	150000	12750
				supplier	mold compound	Phenolic Resin	26834-02-6		0.602	mg	100000	8500
				supplier	mold compound	Carbon Black	1333-86-4		0.030	mg	5000	425